



# *iDiskOnChip (iDOC)* Flash Disk with IDE Interface

Data Sheet, January 2006

### Highlights

iDiskOnChip (iDOC) combines advanced and proven DiskOnChip technology with a standard IDE interface to complement the DiskOnChip product line.

iDiskOnChip provides:

- NAND flash-based technology
- High performance
- Platform independence
- Fast time to market no driver required
- Reed-Solomon code-based EDC/ECC (2 bits/page)
- Wear-leveling mechanism that enables 2 million write/erase cycles for reliable data storage over an extended period
- Fast ATA host transfer rates supporting PIO-4 mode and DMA-2
- IDE master/slave modes of operation
- 40-pin or 44-pin IDE connector
- Vertical and horizontal alignments

#### **IDE Modes**

- PIO modes 0 through 4
- DMA modes 0 through 2

#### Performance

- Host data transfer rate:
  Read: 5 MB/sec
  - $\square$  Write: 4 MB/sec

#### **Power Requirements**

- Single power supply: 5V (±10%) or 3.3V (±5%)
- Current
  - $\Box$  Active mode (typ.): 20 mA
  - $\Box \quad Idle \ mode \ (max): 5 \ mA$



#### **Operating Temperature**

■ Temperature range: 0°C to +70°C

#### **Environmental Conditions**

- Storage temperature:  $-40^{\circ}$ C to  $+ 70^{\circ}$ C
- Sinusoidal vibration: 5g, 7-2000 Hz, 3 axes
- Shock: 50 G, 3 axes

### System Compatibility

 Compatible with devices that support the ATA-4 Attachment for Disk Drive Standard

#### **Capacity and Packaging**

- Available in capacities of 16MB to 1536MB
- Alignments:
  - □ Vertical with or without shell
  - □ Horizontal, left-oriented
  - □ Horizontal, right-oriented

#### **Mechanical Dimensions**

- Vertical version with shell (LxWxH):
  - □ 40-pin: 56.5 x 6.0 x 28.70 (mm)
  - □ 44-pin: 53.2 x 6.5 x 27.85 (mm)
- Vertical version without shell (LxWxH):
  40-pin: 50.5 x 6.2 x 27.2 (mm)
  - $\Box$  44-pin: 46.1 x 4.6 x 26.61 (mm)
- Horizontal version with shell (LxWxH):
  - □ 40-pin: 55.0 x 30.4 x 9.1 (mm)
  - □ 44-pin: 48.0 x 32.6 x 5.9 (mm)



# **REVISION HISTORY**

Revision	Date	Change Description	Reference	
		Updated power consumption parameters	Section 6.4.2	
1.4	October 2004	Added DMA support		
		Added list of supported IDE commands	Section 6.5	
1.5	December 2004	Updated number of write/erase cycles	Sections 3.4, 6.2.5	
1.5	December 2004	Updated ordering information	Section 7	
1.6	March 2005	Added vertical shell-less configuration	Sections 6.3.3.2, 6.3.4.2	
1.7	May 2005	Added new shell for vertical configuration	Section 6.3	
1.7	Way 2005	Added new capacity – 384MB	Section 7	
1.8	August 2005	Updated CHS parameters	Section 6.6	
		Updated write performance parameters	Highlights	
1.9	January 2006	Updated the ordering information for RoHS-compliant products	Section 7	
		Updated storage temperatures	Section 15	



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# 1. INTRODUCTION

This data sheet includes the following sections:

Section 1:	Overview of data sheet contents
Section 2:	Product overview, including brief product description, pin assignment and description
Section 3:	Theory of operation
Section 4:	Installation requirements, including electrical cabling and master/slave configurations
Section 5:	Power management for the various iDiskOnChip operational modes
Section 6:	Product specifications, including mechanical and electrical
Section 7:	Product ordering information and available product configurations

For additional information on M-Systems' flash disk products, please contact one of the offices listed on the back page.



# 2. **PRODUCT OVERVIEW**

# 2.1 Product Description

iDiskOnChip complements the DiskOnChip product line, offering full IDE capabilities, high performance, a built-in ECC system and flexible design options. It can be used in any system with an IDE bus and can work with any operating system, since the driver is handled at the BIOS level.

iDiskOnChip is based on NAND flash technology. This technology is superior in its data storage characteristics, featuring the industry's highest write and erase performance, as well as the highest burst read/write transfer rate. Additionally, NAND flash technology is known for its high density and small die size, with the related cost and real estate benefits. Data integrity is guaranteed through embedded error detection and error correction code (EDC/ECC) that automatically detects and corrects data errors. An on-chip ECC unit generates the required code bytes for error detection and correction of up to 2 bits per 512-byte data sector. Code-byte generation during write operations, as well as error detection during read operation, is implemented on the fly without performance degradation.

iDiskOnChip is ergonomically designed for easy installation and ready-to-run operation. Available in 40-pin and 44-pin connector packages, iDiskOnChip fits easily into any platform with an IDE connector.

The horizontal version is provided in both left and right orientations, giving maximum flexibility for insertion to the host platform.

iDiskOnChip is available in capacities ranging from 16MB to 1536MB, making the upgrade path simple and fast.



# 2.2 Pin Assignment

iDiskOnChip uses a standard IDE pinout. See Table 1 for iDiskOnChip pin assignments.

Pin No.	Signal	Function	Pin No.	Sig	nal	Function
1	RESET#	Host Reset	2	GND		Ground
3	HD7	Host Data Bit 7	4	HD8		Host Data Bit 8
5	HD6	Host Data Bit 6	6	HD9		Host Data Bit 9
7	HD5	Host Data Bit 5	8	HC	)10	Host Data Bit 10
9	HD4	Host Data Bit 4	10	HC	)11	Host Data Bit 11
11	HD3	Host Data Bit 3	12	HC	)12	Host Data Bit 12
13	HD2	Host Data Bit 1	14	HC	)13	Host Data Bit 13
15	HD1	Host Data Bit 1	16	HC	)14	Host Data Bit 14
17	HD0	Host Data Bit 0	18	HC	015	Host Data Bit 15
19	GND	Ground	20	40-pin	VCC <sup>1</sup>	Supply Voltage
19	GND	Ground	20	44-pin	KEY	Cut pin
21	DMARQ	DMA Request	22	GI	ND	Ground
23	HIOW#	Host I/O Write	24	GI	ND	Ground
25	HIOR#	Host I/O Read	26	GND		Ground
27	IORDY	I/O Ready	28	CS	EL	Master/Slave Select
29	DMACK	DMA Acknowledge	30	GI	١D	Ground
31	INTRQ	Interrupt Request	32	IOIS	616#	CS I/O 16-Bit
33	HA1	Host Address Bit 1	34	PDIAG#		Passed Diagnostics
35	HA0	Host Address Bit 0	36	HA2		Host Address Bit 2
37	CS0#	Chip Select 0	38	CS1#		Chip Select 1
39	DASP#	Drive Active/ Drive 1 Present	40	GND		Ground
41 <sup>2</sup>	NC	Not Connected	42 <sup>2</sup>	VC	00	Supply Voltage
43 <sup>2</sup>	GND	Ground	44 <sup>2</sup>	RESE	RVED	Reserved

Table 1: iDiskOnChip Pin Assignment

1. In the 40-pin version, this pin is defined as VCC to reduce the need for an external power connector. In the 44-pin version, this pin is defined as KEY, according to the ATA standard.

2. The 40-pin version does not contain pins 41-44.

NC = These pins are not connected internally.

RESERVED = All reserved signals must be left floating.



# 2.3 Pin Description

Table 2 describes the pin descriptions for iDiskOnChip.

### Table 2: iDiskOnChip Pin Description

Signal	Pin No.	Description		
		System Interface		
HD15-HD0	Host Data bus [15:0]. 16-bit bi-directional data input/output bus. HD15 is the most significant bit, while HD0 is the least significant bit. This bus carries data, commands and status information between the host and iDiskOnChip. The lower 8 bits are used for 8-bit register transfers. Data transfers are 16 bits wide.		I/O	
HA2-HA0	33,35,36	Host Address bus HA[2:0]: Select the registers in the iDiskOnChip controller.	Input	
	<u> </u>	Configuration		
DIOW#	23	Device I/O Write: Active low. Gates the data from the bus to iDiskOnChip. The clocking occurs on the rising edge of the signal.	Input	
DIOR#	25	Device I/O Read: Active low. Gates the data to the bus from iDiskOnChip. The clocking occurs on the falling edge of the signal.		
CSEL	28 Configuration Select: Determines the device configuration as either Master or Slave. If CSEL is negated, then the device address is Master; if CSEL is asserted, then the device address is Slave.		Input	
CS0#	37	Host Chip Select 0: Active low. Selects the Command Block registers.	Input	
CS1#	38	Host Chip Select 1: Active low. Selects the Command Block registers.		
	Control			
RESET#	1	Host reset: Active low.	Input	
IORDY	27	I/O Ready: Negated by iDiskOnChip to extend the host transfer cycle (read or write) when the device is not ready to respond to a data transfer request.	Output	



Signal	Pin No.	Description	Signal Type	
		DMA Request: This signal, used for DMA data transfers between the host and iDiskOnChip, is asserted by iDiskOnChip when it is ready to transfer data to or from the host.		
DMARQ	21	The direction of data transfer is controlled by DIOR# and DIOW#. This signal is used in a handshake manner with DMACK#, meaning iDiskOnChip waits until the host asserts DMACK# before negating DMARQ, and re-asserting DMARQ if there is more data to transfer.	Output	
		This line is released (high impedance state) whenever iDiskOnChip is not selected, or is selected and no DMA command is in progress.		
		When enabled by DMA transfer, DMARQ is driven high and low by the device.		
		When a DMA operation is enabled, CS0# and CS1# are asserted and transfers are 16 bits wide.	Input	
DMACK	29	DMA Acknowledge: This signal shell be used by the host in response to DMARQ to initiate DMA transfers		
INTRQ	31	Interrupt Request: Interrupt request from iDiskOnChip to the host. The output of this signal is tri-stated if the host disables the interrupt. When asserted, this signal is negated by the device within 400 nsec of the negation of the DIOR# signal that reads the Status register. When asserted, this signal is negated by the device within 400 nsec of the negation of the DIOW# signal that writes the Command register.		
IOIS16#	32	I/O IS I6-Bit: Active low. Asserted (low) by iDiskOnChip to indicate		
	•	Status		
PDIAG#	34	Passed Diagnostics: Active low. Informs the Master drive that the self-diagnostic of the Slave drive has ended.	I/O	
DASP#	39	Drive Active/Drive1 Present: Active low. This is a time-multiplexed signal that indicates that a device is active, or that Device 1 is present.		
		Power		
GND	GND 2,19,22,24,2 6,30,40,43 Ground		Ground	
VCC	42	Power supply		
		Other		
NC	41, 44	Not connected	N/A	



# 3. THEORY OF OPERATION

### 3.1 Overview

Figure 1 shows iDiskOnChip operation from the system level, including the major hardware blocks.

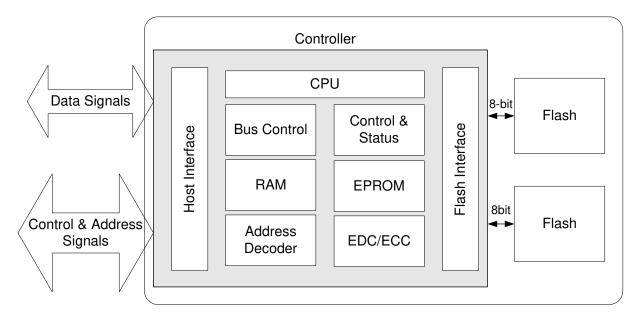


Figure 1: iDiskOnChip Block Diagram

iDiskOnChip integrates an IDE controller and flash devices. Communication with the host occurs through the host interface, using the standard ATA protocol. Communication with the flash device(s) occurs through the flash interface.

# 3.2 Controller

The controller is equipped with 16KB of internal memory that is used for storing code and data. The internal memory can also be used as an intermediate memory for storing data blocks during a wear-leveling procedure.

An 8KB internal boot ROM includes basic routines for accessing the flash memories and for loading the main code into the internal memory

The host interface provides all required signals, is fully compliant with the PC Card standard, and supports True-IDE mode operation requirements.

# 3.3 Error Detection and Correction

Highly sophisticated Error Correction Code algorithms are implemented. The ECC unit consists of the Parity Unit (parity-byte generation) and the Syndrome Unit (syndrome-byte computation). This unit implements a Reed-Solomon algorithm that can correct two bits per 512 bytes in an ECC block. Code-byte generation during write operations, as well as error detection during read operation, is implemented on the fly without any speed penalties.



# 3.4 Wear-Leveling

Flash memory can be erased a limited number of times. This number is called the *erase cycle limit* or *write endurance limit* and is defined by the flash array vendor. The erase cycle limit applies to each individual erase block in the flash device.

iDiskOnChip uses a wear-leveling algorithm to ensure that consecutive writes of a specific sector are not written physically to the same page in the flash. This spreads flash media usage evenly across all pages, thereby maximizing flash lifetime.

iDiskOnChip sustains more than two million write/erase cycles and an unlimited number of read cycles.



## 4. INSTALLATION REQUIREMENTS

## 4.1 iDiskOnChip Pin Directions

Figure 2 and Figure 3 illustrate the iDiskOnChip pin directions in the vertical version.

As the horizontal version uses the same connector, the same pin directions can be used for the horizontal models.





Figure 2: 40-Pin (Vertical with Shell) iDiskOnChip Connector Layout





Figure 3: 44-Pin (Vertical with Shell) iDiskOnChip Connector Layout

# 4.2 iDiskOnChip Left/Right Orientation, Horizontal Version

The right-oriented iDiskOnChip, when held as shown in Figure 4, has pin 1 on the right side. The left-oriented iDiskOnChip, when held as shown in Figure 5, has pin 1 on the left side.



Figure 4: iDiskOnChip Horizontal Version 40 pin, Right-Oriented



Figure 5: iDiskOnChip Horizontal Version 44 pin, Left-Oriented



# 4.3 Electrical Connections for iDiskOnChip

iDiskOnChip can be connected to the host by placing it directly on the on-board socket. If a cable is used, it should be no longer than 18 inches, and should be aligned as follows:

- For 44-pin iDiskOnChip:
  - o Pin 1 of the cable must be aligned with pin 1 of the iDiskOnChip connector.
  - o Pin 44 of the cable must be aligned with pin 44 of the iDiskOnChip connector.
- For 40-pin iDiskOnChip:
  - o Pin 1 of the cable must be aligned with pin 1 of the iDiskOnChip connector.
  - o Pin 40 of the cable must be aligned with pin 40 of the iDiskOnChip connector.

The 40-pin iDiskOnChip version has a separate connector for the power supply, to which a power supply cable can be connected. In addition, pin 20 can also be used for power supply connections. Please refer to the pin description for further details.

Note: For a list of recommended connectors, contact an M-Systems representative.

## 4.4 Installing iDiskOnChip in a Two-Drive Configuration (Master/Slave)

If iDiskOnChip is being installed as an additional IDE drive using the same IDE I/O port, jumper J1 must be set to indicate that this drive is a slave. The default is master with no jumpers. Table 3 shows the J1 jumper settings for iDiskOnChip operation in Master and Slave mode.

J1 Jumper Settings	Operation Mode
No jumper is installed (open)	Master
Jumper is installed (short)	Slave

Table 3: Jumper Settings for Master/Slave Mode

### 4.4.1 Vertical Configuration

The vertical configuration can operate in either Master or Slave mode. The following figures show the jumper settings for the iDiskOnChip vertical configuration.

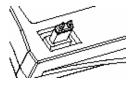


Figure 6: Slave Setting for Vertical iDiskOnChip 44-Pin Connector

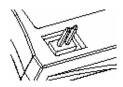


Figure 8: Master Setting for Vertical iDiskOnChip 44-Pin Connector

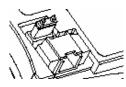


Figure 7: Slave Setting for Vertical iDiskOnChip 40-Pin Connector



Figure 9: Master Setting for Vertical iDiskOnChip 40-Pin Connector



### 4.4.2 Horizontal Configuration

The horizontal configuration can operate in either Master or Slave mode. The mode can be set via the device jumper settings. In addition, the jumpers can be set to cable select. The following figures show the jumper settings for iDiskOnChip horizontal configuration.

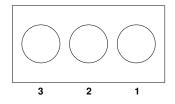


Figure 10: Jumper Not Installed, iDiskOnChip Configured as Master

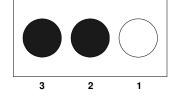


Figure 11: Jumper Installed on Pins 2-3, iDiskOnChip Configured According to Cable Select

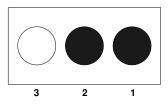


Figure 12: Jumper Installed on Pins 1-2, iDiskOnChip Configured as Slave



# 5. **POWER MANAGEMENT**

iDiskOnChip has three operational modes, listed below. Idle and Sleep modes provide automatic power management.

- Active: If the iDiskOnChip controller receives any Command In or Soft Reset, it enters Active mode. In Active mode, iDiskOnChip can execute any supported ATA command. The power consumption level is the highest in this mode.
- Idle: After the iDiskOnChip controller executes any ATA command or Soft Reset, it automatically enters Idle mode. Power consumption is reduced as compared with Active mode.
- Sleep: The iDiskOnChip controller automatically transfers the device from Idle into Sleep mode if there is no Command In or Soft Reset from the host for about 16 ms. This time interval can be modified by firmware if necessary. In Sleep mode, iDiskOnChip power consumption is at its lowest level. During Sleep mode, the system main clock is stopped. This mode can be released through a hardware reset, software reset, or when any ATA command is asserted.



## 6. **SPECIFICATIONS**

## 6.1 CE and FCC Compatibility

iDiskOnChip conforms to CE requirements and FCC standards.

### 6.2 Environmental Specifications

### 6.2.1 Temperature Ranges

Temperature Range  $0^{\circ}$ C to  $+70^{\circ}$ C

Storage Temperature:  $-40^{\circ}$ C to  $+70^{\circ}$ C

### 6.2.2 Humidity

Relative Humidity: 10-95%, non-condensing

#### 6.2.3 Shock and Vibration

#### Table 4: Shock/Vibration Testing for iDiskOnChip

Reliability Tests	Test Conditions	Reference Standards
Vibration	7 Hz to 2000 Hz, 5 g, 3 axes	IEC 68-2-6
Mechanical Shock	Duration: 10 ms, 50 g, 3 axes	IEC 68-2-27
Drop Unit	From a height of 1.5 m	IEC 68-2-32

### 6.2.4 Mean Time between Failures (MTBF)

Table 5 summarizes the MTBF prediction results for various iDiskOnChip configurations. The analysis was performed using a RAM Commander<sup>TM</sup> failure rate prediction.

- **Failure Rate**: The total number of failures within an item population, divided by the total number of life units expended by that population, during a particular measurement interval under stated condition.
- Mean Time Between Failures (MTBF): A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

Table 5: iDiskOnChip MTBF	

Product	Condition	MTBF (Hours)	Failure Rate per Million Hours
Vertical 40-pin	- Telcordia SR-332 GB, 25°C -	5,267,540	0.1898
Horizontal 40-pin		4,650,009	0.2151
Vertical 44-pin		6,188,875	0.1616
Horizontal 44-pin		6,102,525	0.1639



### 6.2.5 Endurance

iDiskOnChip sustains more than two million write/erase cycles and an unlimited number of read cycles. Performance is enhanced by the following features:

## 6.3 Mechanical Dimensions

### 6.3.1 40-Pin Horizontal Version

Figure 13 shows the mechanical dimensions of both left- and right-oriented iDiskOnChip, 40-pin horizontal version.

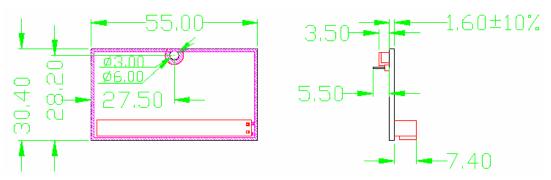


Figure 13: Mechanical Dimensions of iDiskOnChip, 40-Pin Horizontal Version

### 6.3.2 44-Pin Horizontal Version

Figure 14 shows the mechanical dimensions of left-oriented iDiskOnChip, 44-pin horizontal version.

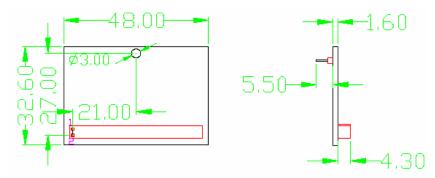


Figure 14: Mechanical Dimensions of iDiskOnChip, 44-Pin Horizontal Version



### 6.3.3 40-Pin Vertical Version

### 6.3.3.1 With Shell

Figure 15 shows the mechanical dimensions of iDiskOnChip, 40-pin vertical version with a shell.

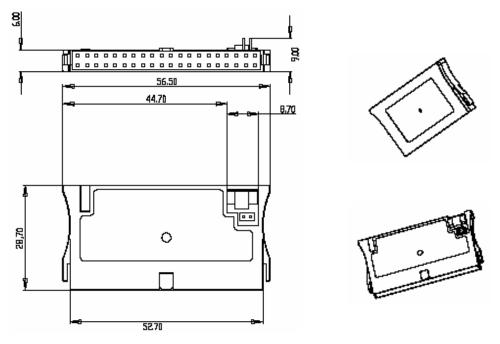


Figure 15: Dimensions of iDiskOnChip, 40-Pin Vertical Version with Shell

#### 6.3.3.2 Without Shell

Figure 16 shows the mechanical dimensions of iDiskOnChip, 40-pin vertical version without a shell.

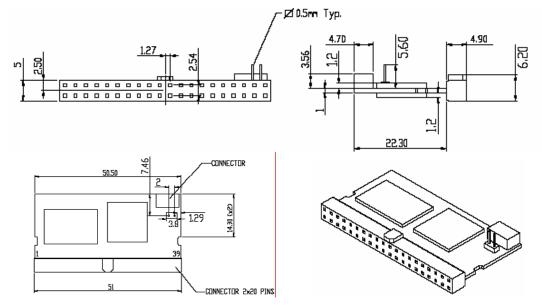


Figure 16: Dimensions of iDiskOnChip, 40-Pin Vertical Version Without Shell



### 6.3.4 44-Pin Vertical Version

### 6.3.4.1 With Shell

Figure 17 shows the mechanical dimensions of iDiskOnChip, 44-pin vertical version with a shell.

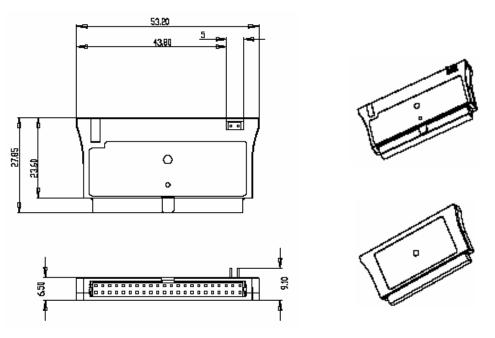


Figure 17: Dimensions of iDiskOnChip, 44-Pin Vertical Version with Shell

#### 6.3.4.2 Without Shell

Figure 18 shows the mechanical dimensions of iDiskOnChip, 44-pin vertical version without a shell.

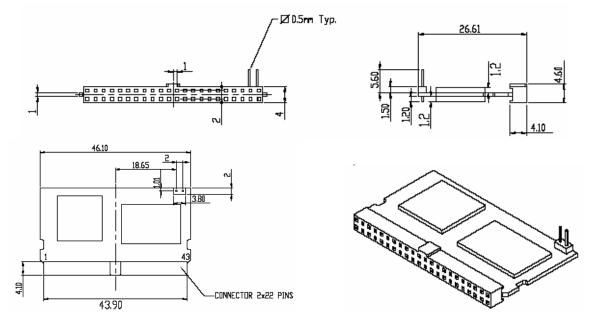


Figure 18: Dimensions of iDiskOnChip, 44-Pin Vertical Version



## 6.4 Electrical Specifications

### 6.4.1 Absolute Maximum Ratings

Table 6: iDiskOnChip Absolute Maximum Ratings

Symbol	Parameter	Min	Мах	Unit
V <sub>IN</sub>	Input Voltage (5v)	4.5	5.5	V
V <sub>IN</sub>	Input Voltage (3.3v)	3.13	3.43	V
Ta	Operating Temperature	0	+70	°C
T <sub>st</sub>	Storage Temperature	-40	+80	°C

#### 6.4.2 DC Characteristics

Symbol	Parameter	Min	Max	Unit
V <sub>IH</sub>	Input High voltage	2.5	Vcc +0.3	V
V <sub>IL</sub>	Input Low voltage	-0.3	0.8	V
V <sub>OH</sub>	Output High voltage	2.4	-	V
V <sub>OL</sub>	Output Low voltage	-	0.45	V
I <sub>cc</sub>	Operating current		60 mA (max); 20mA (typ)	mA
I <sub>ccs</sub>	Standby mode current (*)	-	5 mA (max)	mA
ILI	Input leakage current	-	±20	μA
I <sub>LO</sub>	Output leakage current	-	±20	μA

Ta=0°C to +70°C, Vcc= $5.0V \pm 10$ 

\*Measured with flash memory and host interface

#### 6.4.3 AC Characteristics

### Table 8: Timing Specifications, PIO Mode 4

Symbol	Parameter		Max	Unit
tcR	Cycle time	120		ns
tsuA	Address setup time for IORD/IOWR	25		ns
thA	Address hold time from IORD/IOWR	10		ns
tw	IORD/IOWR pulse width	70		ns
trec	IORD/IOWR recovery time	25		ns
tsuD(IORD)	Data setup time for IORD	20		ns
thD(IORD)	Data hold following IORD	5		ns
tdis(IORD)	Output disable time from IORD		30	ns
tsuD(IOWR)	Data setup time for IOWR	20		ns
thD(IOWR)	Data hold following IOWR	10		ns



# 6.5 Supported IDE Commands

iDiskOnChip supports the commands listed in Table 9.

### Table 9: IDE Commands

Command Name	Command Code	
CHECK POWER MODE	98h E5h	
EXECUTE DEVICE DIAGNOSTIC	90h	
FORMAT TRACK	50h	
IDENTIFY DEVICE	Ech	
IDLE	97h E3h	
IDLE IMMEDIATE	95h E1h	
INITIALIZE DEVICE PARAMETERS	91h	
READ BUFFER	E4h	
READ DMA (with retry)	C8h	
READ DMA (without retry)	C9h	
READ MULTIPLE	C4h	
READ SECTOR(S) (with retry)	20h	
READ SECTOR(S) (without retry)	21h	
READ LONG	22h 23h	
READ VERIFY SECTOR(S) (with retry)	40h	
READ VERIFY SECTOR(S) (without retry)	41h	
RECALIBRATE	10h	
SEEK	70h	
SET FEATURES	Efh	
SET MULTIPLE MODE	C6h	
SLEEP	99h E6h	
STANDBY	96h E2h	
STANDBY IMMEDIATE	94h E0h	
WRITE BUFFER	E8h	
WRITE DMA (with retry)	CAh	
WRITE DMA (without retry)	CBh	
WRITE MULTIPLE	C5h	
WRITE SECTOR(S) (with retry)	30h	
WRITE SECTOR(S) (without retry)	31h	
WRITE LONG	32h 33h	



# 6.6 Cylinder Head Sector (CHS) Parameters

Table 10: CHS Parameters for iDiskOnChip

iDiskOnChip Capacity (MB)	CHS Parameters		
	Cylinder	Head	Sector
16	490	2	32
32	500	8	16
64	500	8	32
128	500	16	32
192	750	16	32
256	1000	16	32
384	745	16	63
512	1015	16	63
768	1522	16	63
1024	2044	16	63
1536	3067	16	63



# 7. ORDERING INFORMATION

### MD11AC-DXXXX-W-P

Where:

MD11	M-Systems' iDiskOnChip product
Α	5: Vertical alignment
	6: Horizontal alignment, left oriented
	7: Horizontal alignment, right oriented
С	0: 40-pin IDE connector
	1: 44-pin IDE connector
W	W (vertical configuration only): Without shell
	Blank (vertical configuration only): With shell
Ρ	P: RoHS-compliant version
	Blank: Non-ROHS-compliant version

**DXXXX** Capacity (MB): 16, 32, 64, 128, 192, 256, 384, 512, 768, 1024, 1536

Refer to Table 11 for the combinations currently available and the associated ordering information. *Table 11: Available Combinations* 

Capacity (MB)	IDE Connector	Alignment	Ordering Code
	40-pin	Vertical	MD1150-D16-P
		Vertical (without shell)	MD1150-D16-W-P
		Horizontal (left)	MD1160-D16-P
16		Horizontal (right)	MD1170-D16-P
10	44-pin	Vertical	MD1151-D16-P
		Vertical (without shell)	MD1151-D16-W-P
		Horizontal (left)	MD1161-D16-P
		Horizontal (right)	MD1171-D16-P
	40-pin	Vertical	MD1150-D32-P
		Vertical (without shell)	MD1150-D32-W-P
		Horizontal (left)	MD1160-D32-P
32		Horizontal (right)	MD1170-D32-P
32	44-pin	Vertical	MD1151-D32-P
		Vertical (without shell)	MD1151-D32-W-P
		Horizontal (left)	MD1161-D32-P
		Horizontal (right)	MD1171-D32-P



Capacity (MB)	IDE Connector	Alignment	Ordering Code
	40-pin	Vertical	MD1150-D64-P
		Vertical (without shell)	MD1150-D64-W-P
		Horizontal (left)	MD1160-D64-P
64		Horizontal (right)	MD1170-D64-P
04		Vertical	MD1151-D64-P
	44 - 21	Vertical (without shell)	MD1151-D64-W-P
	44-pin	Horizontal (left)	MD1161-D64-P
		Horizontal (right)	MD1171-D64-P
		Vertical	MD1150-D128-P
	40 pip	Vertical (without shell)	MD1150-D128-W-P
	40-pin	Horizontal (left)	MD1160-D128-P
128		Horizontal (right)	MD1170-D128-P
120	44-pin	Vertical	MD1151-D128-P
		Vertical (without shell)	MD1151-D128-W-P
		Horizontal (left)	MD1161-D128-P
		Horizontal (right)	MD1171-D128-P
		Vertical	MD1150-D192-P
	40 pip	Vertical (without shell)	MD1150-D192-W-P
	40-pin	Horizontal (left)	MD1160-D192-P
192		Horizontal (right)	MD1170-D192-P
192		Vertical	MD1151-D192-P
	44-pin	Vertical (without shell)	MD1151-D192-W-P
		Horizontal (left)	MD1161-D192-P
		Horizontal (right)	MD1171-D192-P
		Vertical	MD1150-D256-P
	10 nin	Vertical (without shell)	MD1150-D256-W-P
	40-pin	Horizontal (left)	MD1160-D256-P
256		Horizontal (right)	MD1170-D256-P
200	44-pin	Vertical	MD1151-D256-P
		Vertical (without shell)	MD1151-D256-W-P
		Horizontal (left)	MD1161-D256-P
		Horizontal (right)	MD1171-D256-P



Capacity (MB)	IDE Connector	Alignment	Ordering Code
		Vertical	MD1150-D384-P
	40 pip	Vertical (without shell)	MD1150-D384-W-P
	40-pin	Horizontal (left)	MD1160-D384-P
004		Horizontal (right)	MD1170-D384-P
384		Vertical	MD1151-D384-P
		Vertical (without shell)	MD1151-D384-W-P
	44-pin	Horizontal (left)	MD1161-D384-P
		Horizontal (right)	MD1171-D384-P
		Vertical	MD1150-D512-P
	10 pip	Vertical (without shell)	MD1150-D512-W-P
	40-pin	Horizontal (left)	MD1160-D512-P
512		Horizontal (right)	MD1170-D512-P
512	44-pin	Vertical	MD1151-D512-P
		Vertical (without shell)	MD1151-D512-W-P
		Horizontal (left)	MD1161-D512-P
		Horizontal (right)	MD1171-D512-P
		Vertical	MD1150-D768-P
		Vertical (without shell)	MD1150-D768-W-P
	40-pin	Horizontal (left)	MD1160-D768-P
768		Horizontal (right)	MD1170-D768-P
700		Vertical	MD1151-D768-P
	44-pin	Vertical (without shell)	MD1151-D768-W-P
		Horizontal (left)	MD1161-D768-P
		Horizontal (right)	MD1171-D768-P
		Vertical	MD1150-D1024-P
	40-pin	Vertical (without shell)	MD1150-D1024-W-P
		Horizontal (left)	MD1160-D1024-P
1024		Horizontal (right)	MD1170-D1024-P
1024	4	Vertical	MD1151-D1024-P
		Vertical (without shell)	MD1151-D1024-W-P
		Horizontal (left)	MD1161-D1024-P
		Horizontal (right)	MD1171-D1024-P



Capacity (MB)	IDE Connector	Alignment	Ordering Code
	40-pin	Vertical	MD1150-D1536-P
		Vertical (without shell)	MD1150-D1536-W-P
1536		Horizontal (left)	MD1160-D1536-P
		Horizontal (right)	MD1170-D1536-P
	44	Vertical	MD1151-D1536-P
		Vertical (without shell)	MD1151-D1536-W-P
	44-pin	Horizontal (left) MD1161-	MD1161-D1536-P
		Horizontal (right)	MD1171-D1536-P

Note: The 40-pin iDiskOnChip requires an additional cable for the power supply. The ordering information is: DOC-IDE40-CABLE



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